Product / Package Information

Package	LGA
Body Size (mm)	3 X 3.25
I/O Count	16
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0 / 14808-60-7	9.30E-03	94.50	945000	48.03	480285
Thermosets	Epoxy resin	Proprietary	1.97E-04	2.00	20000	1.02	10165
Thermosets	Phenol Resin	Proprietary	1.97E-04	2.00	20000	1.02	10165
Other inorganic materials	Metal Hydroxide	Proprietary	9.84E-05	1.00	10000	0.51	5082
Other inorganic materials	Carbon Black	1333-86-4	4.92E-05	0.50	5000	0.25	2541
Subtotal			9.84 E-03	100.00	1000000	50.82	508239

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Cured thermosetting resin (including inorganic filler)	Proprietary	8.03 E-04	17.833	178326	4.15	41506
Composite	Continuous Filament Fiber Glass	Proprietary	8.03 E-04	17.830	178300	4.15	41500
Composite	Copper	7440-50-8	1.07 E-03	23.772	237720	5.53	55330
	Laminate Core Subtotal		2.68 E-03	59.435	594346	13.83	138336
Other organic materials	Acrylate Resin	Proprietary	3.98 E-04	8.831	88311	2.06	20555
Other organic materials	Copper phthalocyanine	Proprietary	9.69 E-07	0.022	215	0.01	50
Other inorganic materials	Organic pigment	Proprietary	9.69 E-07	0.022	215	0.01	50
Other inorganic materials	Silicon dioxide	7631-86-9	5.94 E-05	1.319	13189	0.31	3070
Other inorganic materials	Barium sulfate	7727-43-7	5.94 E-05	1.319	13189	0.31	3070
Other inorganic materials	Talc	14807-96-6	5.94 E-05	1.319	13189	0.31	3070
Other inorganic materials	Organic filler	Proprietary	5.94 E-05	1.319	13189	0.31	3070
Others	Antifoamer and Leveling agent	Proprietary	8.40 E-06	0.186	1864	0.04	434
	Soldermask Subtotal		6.46 E-04	14.336	143361	3.34	33368
Copper & its alloys	Copper	7440-50-8	1.02 E-03	22.603	226034	5.26	52610
Nickel & its alloys	Nickel	7440-02-0	1.34 E-04	2.980	29802	0.69	6937
Precious metals	Gold	7440-57-5	2.91 E-05	0.646	6457	0.15	1503
Subtotal			4.51 E-03	100.00	1000000	23.28	232753

Cap Seal

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Aluminum & its alloys	Aluminum	7429-90-5	4.42 E-04	50.00	500000	2.28	22847
Other inorganic materials	Germanium	7440-56-4	2.21 E-04	25.00	250000	1.14	11423
Aluminum & its alloys	Copper	7440-50-8	1.33 E-04	15.00	150000	0.69	6854
Other inorganic materials	Tungsten	7440-33-7	7.08 E-05	8.00	80000	0.37	3655
Other inorganic materials	Titanium	7440-32-6	1.77 E-05	2.00	20000	0.09	914
Subtotal			8.85 E-04	100.0	1000000	4.57	45693

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.71 E-05	99.0	990000	0.35	3468
Precious metals	Palladium	7440-05-3	6.78 E-07	1.0	10000	0.00	35
Subtotal			6.78 E-05	100.0	1000000	0.35	3503

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.65 E-03	100.0	1000000	18.84	188371

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon dioxide	60676-86-0	1.00 E-04	48.30	483000	0.52	5178
Other organic materials	Bismaleimide monomer	TS #10049	6.49 E-05	31.25	312500	0.34	3350
Other organic materials	Acrylate monomer	TS #10050	1.77 E-05	8.52	85200	0.09	913
Thermoset	Epoxy resin	TS #10042	1.77 E-05	8.52	85200	0.09	913
Other organic materials	Acryric resin	TS #10051	7.08 E-06	3.41	34100	0.04	366
Subtotal			2.08 E-04	100.0	1000000	1.07	10721

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	1.04 E-04	50.00	500000	0.54	5360
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	9.34 E-05	45.00	450000	0.48	4824
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	1.04 E-05	5.00	50000	0.05	536
			2.08 E-04	100.0	1000000	1.07	10721

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.94 E-02**	**100.00**	**1000000**

Control ID:MS011761PKG3967

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

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